

TIS75

N-Channel General Purpose Amplifier

- This device is designed for low level analog switching, sample and hold circuits and chopper stabilized amplifiers.
- Sourced from process 54.



1. Gate 2. Source 3. Drain

Absolute Maximum Ratings * T_a=25°C unless otherwise noted

Symbol	Parameter	Value	Units
V_{DG}	Drain-Gate Voltage	30	V
V_{GS}	Gate-Source Voltage	-30	V
I _{GF}	Forward Gate Current	10	mA
T _J , T _{STG}	Operating and Storage Junction Temperature Range	-55 ~ +150	°C

^{*} These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

- These ratings are based on a maximum junction temperature of 150 degrees C.
 These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.

Electrical Characteristics T_a=25°C unless otherwise noted

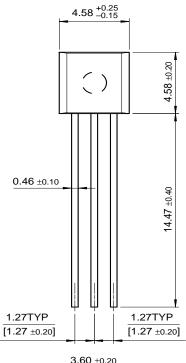
Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Units	
Off Characteristics							
V _{(BR)GSS}	Gate-Source Breakdown Voltage	$I_G = 1.0 \mu A, V_{DS} = 0$	-30			V	
I_{GSS}	Gate Reverse Current	$V_{GS} = 15V, V_{DS} = 0$ $V_{GS} = 15V, V_{DS} = 0, T_a = 100^{\circ}C$			-2.0 -5.0	nA μA	
I _D (off)	Drain Cutoff Leakage Current	$V_{DS} = 15V$, $V_{DS} = 0$, $V_{DS} = 15V$, $V_{DS} = -10V$, $V_{DS} = 15V$, $V_{GS} = -10V$, $V_{DS} = 15V$, $V_{GS} = -10V$, $V_{DS} = 100$ °C			-2.0 -5.0	nA μA	
V _{GS} (off)	Gate-Source Cutoff Voltage	$V_{DS} = 20V, I_D = 4.0nA$	-0.8		-4.0	V	
On Charac	cteristics *	•	•				
I _{DSS}	Zero-Gate Voltage Drain Current *	V _{DS} = 15V, V _{GS} = 0	8		80	mA	
r _{DS} (on)	Drain-Source On Resistance	$V_{DS} \le 0.1 V, V_{GS} = 0$			60	Ω	
Small Sigr	nal Characteristics	•	-				
C _{iss}	Input Capacitance	$V_{DS} = 0$, $V_{GS} = -10V$, $f = 1.0MHz$			18	pF	
C _{rss}	Reverse Transfer Capacitance	$V_{DS} = 0$, $V_{GS} = -10V$, $f = 1.0MHz$			8.0	pF	
Switching	Characteristics		•			•	
t _r	Rise Time	$V_{GS}(off) = -4.0V, V_{GS}(on) = 0,$			10	ns	
t _{on}	Turn-On Time	$I_D = 5.0 \text{mA}, V_{DS} = 10 \text{V}$			10	ns	
t _{off}	Turn-Off Time				100	ns	

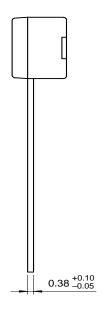
^{*} Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 3.0%

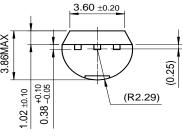
Thermal Characteristics T _a =25°C unless otherwise noted				
Symbol	Parameter	Max.	Units	
P _D	Total Device Dissipation Derate above 25°C	350 2.8	mW mW/ ^o C	
$R_{\theta JC}$	Thermal Resistance, Junction to Case	125	°C/W	
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	357	°C/W	

Package Dimensions

TO-92







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